



Product Change Notification - KSRA-22BMJF664

Date:

27 Apr 2018

Product Category:

Ethernet PHYs

Affected CPNs:**Notification subject:**

CCB 2755 Final Notice: Qualification of ASE assembly site for selected products available in 48L LQFP (7x7mm) package using CuPdAu wire, CRM1076WA die attach and G631H molding compound material.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE assembly site for selected products available in 48L LQFP (7x7mm) package using palladium coated copper with gold flash (CuPdAu) wire, CRM1076WA die attach and G631H molding compound material.

Pre Change:

Assembled at TICIP assembly site using silver (Ag) wire, EN4900 die attach and CEL-9200 mold compound.

Post Change:

Assembled at ASE assembly site using palladium coated copper with gold flash (CuPdAu) wire, CRM1076WA die attach and G631H mold compound.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc. (ASE)
Wire material	Ag wire	CuPdAu wire
Die attach material	EN4900	CRM1076WA
Molding compound material	CEL-9200	G631H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying ASE assembly site.

Change Implementation Status:

In Progress



Estimated First Ship Date:

May 27, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2016					->	April 2018					May 2018				
	Workweek	40	41	42	43		44	14	15	16	17	18	19	20	21	22
Initial PCN Issue Date		X														
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date														X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

October 3, 2016: Issued initial notification.

October 6, 2016: Re-issued the initial notification to notify all affected customers.

April 27, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on May 27, 2018.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-22BMJF664_Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8081MLXCA

KSZ8081MLXCA-TR

KSZ8081MLXIA

KSZ8081MLXIA-TR

KSZ8091MLXCA

KSZ8091MLXCA-TR

KSZ8091MLXIA